

Demystifying Edge Launch Connectors

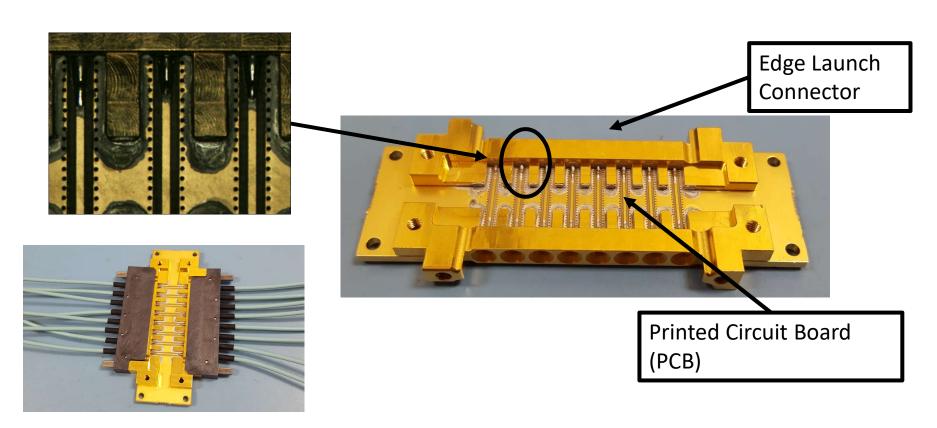
Raul Stavoli, Davi Correia, Emad Soubh, Carlisle Interconnect Technologies



- What is a RF edge launch connector?
- Identify the problem
 - Field leakage
 - Ground and signal discontinuities
- Proposed Solutions
 - Matching the size of the printed circuit board (PCB) dielectric layer and connector signal pin
 - Edge platting of PCB
- Conclusion and next steps

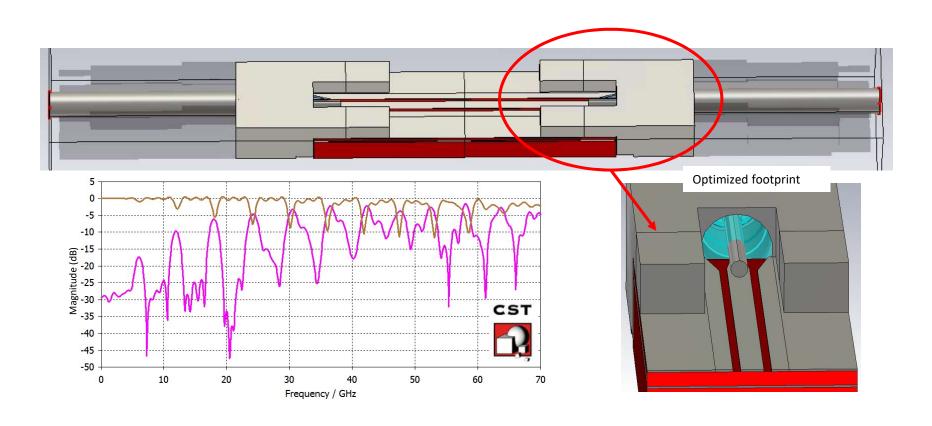


Example 1: Typical RF edge launch connector





Example 2: Typical RF edge launch connector

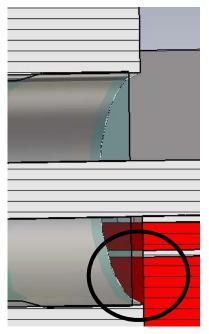




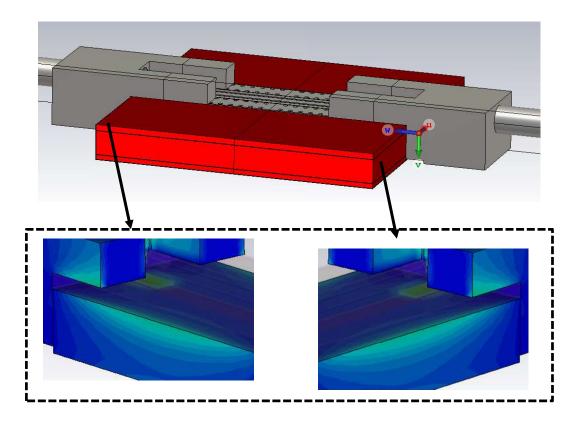
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Field Leakage



Internal PCB Ground not aligned to connector ground

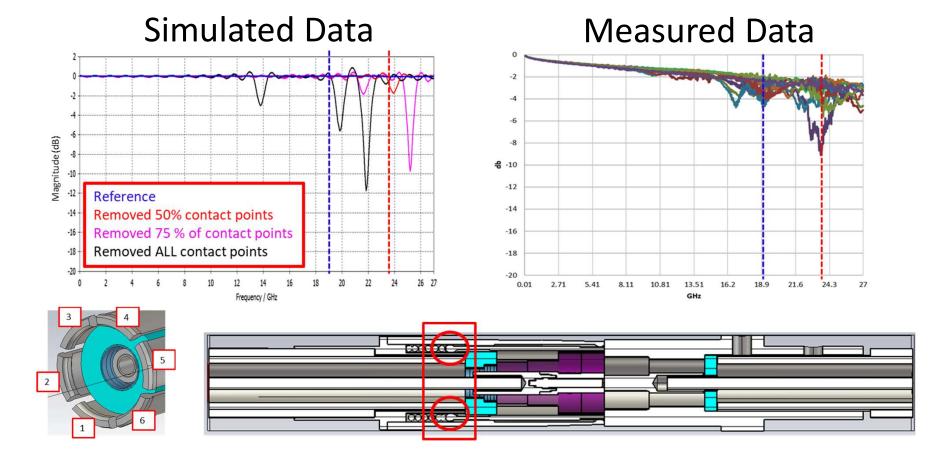




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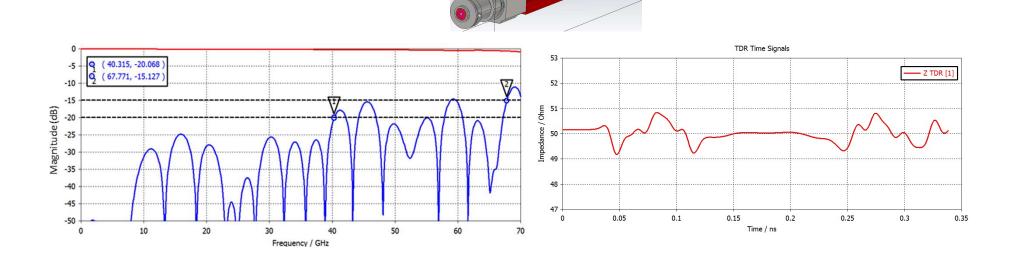
Ground Discontinuities (1)





Ground Discontinuities (2)

- Assembly utilized to characterize RF edge launch interconnect
- All geometric dimensions and locations are nominal

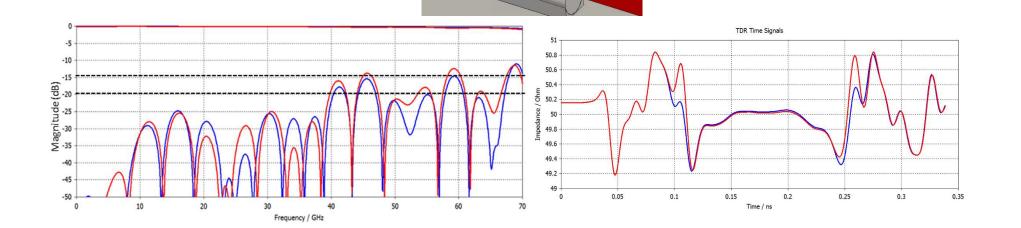




Ground Discontinuities (3)

Co-Planar ground pulled back 0.127mm/5 mils from the edge

of the board

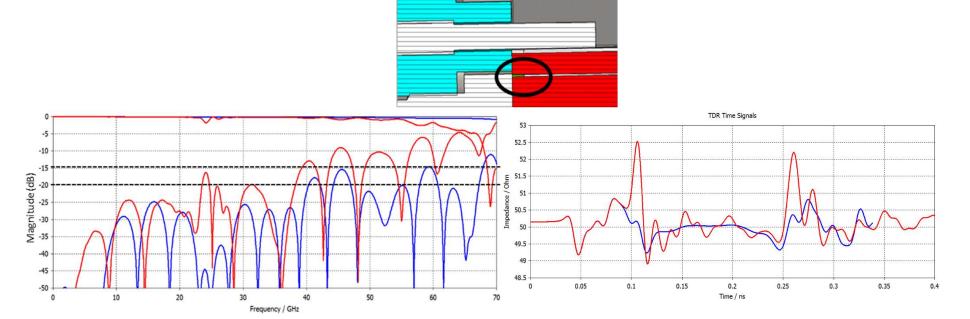




Ground Discontinuities (4)

First internal ground plane pulled back 0.127mm/5 mils from

the edge of the board

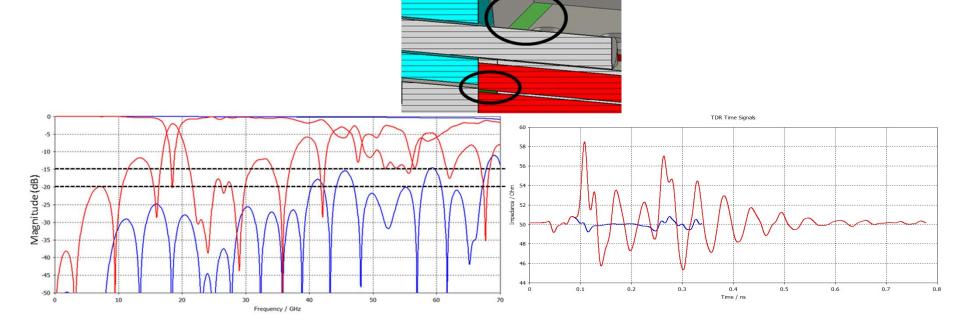




Ground Discontinuities (5)

Top two ground plane layers pulled back 0.127mm/5 mils from

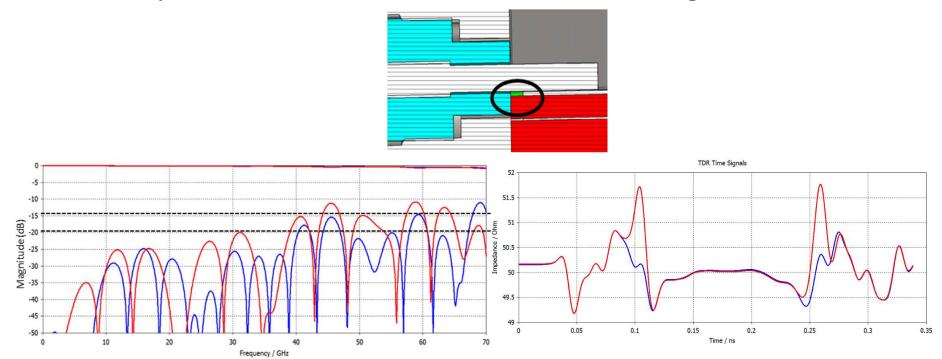
the edge of the board





Signal Discontinuities

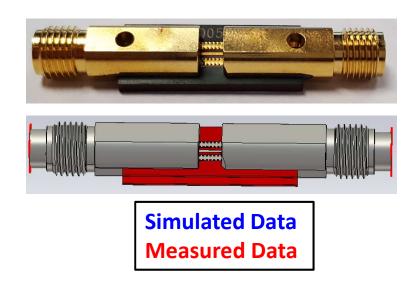
Trace pulled back 0.127mm/5 mils from the edge of the board

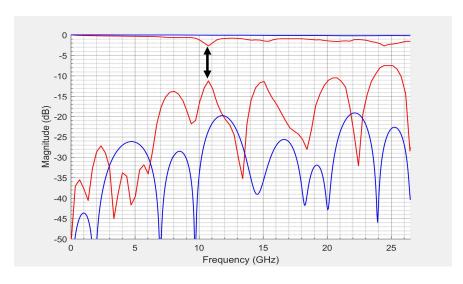




Ground Discontinuities (Example)

- Performance degraded due to ground discontinuities present at the interface w/PCB
- Connectors did not undergo the correct soldering process







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Proposed Solutions

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Proposed Solutions (1)

- Match the size of the PCB dielectric layer and connector signal pin.
 - Proper ground structure alignment to prevent field leakage
- Edge platting:
 - Minimizes the ground discontinuities at the transition from the connector to the board
 - Prevents field leakage when a larger top dielectric layer on the board is not possible



Proposed Solutions (2)

- Placement of:
 - Vias → Line the co-planar structure on the board with vias to channel the fields in the direction of propagation
 - Connector → Flush against the edge of the PCB to prevent field leakage and a degradation of performance at higher frequencies (PCB edge can be milled down)

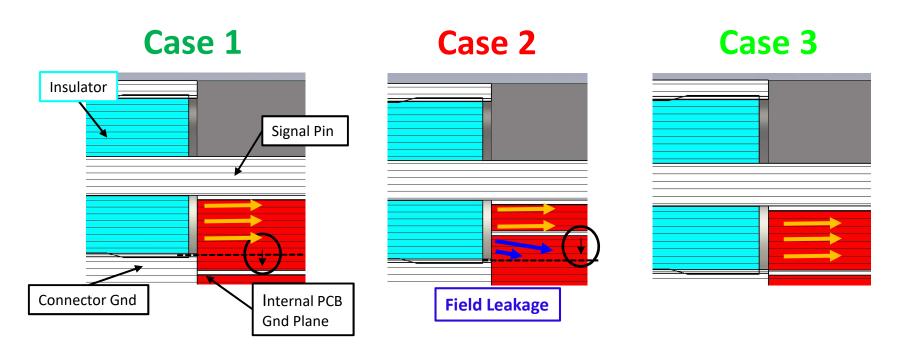


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Ground Structure Alignment

 A misalignment of the connector ground and the internal PCB ground plane can lead to resonances.





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Edge Platting

Addresses improper ground structure alignment

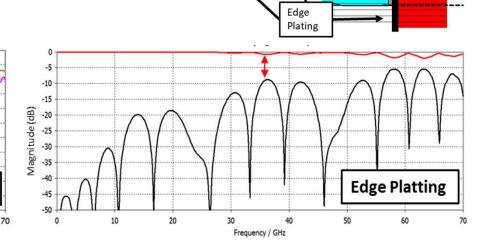
No Edge Platting

Prevents field leakage

-45 -50

Minimizes ground discontinuities

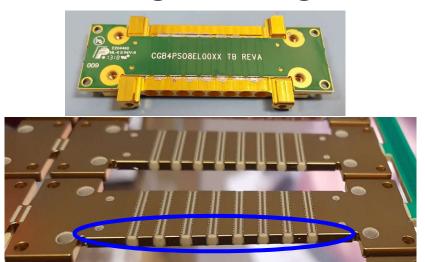
Frequency / GHz





Edge Platting Experiment (1)

Edge Platting



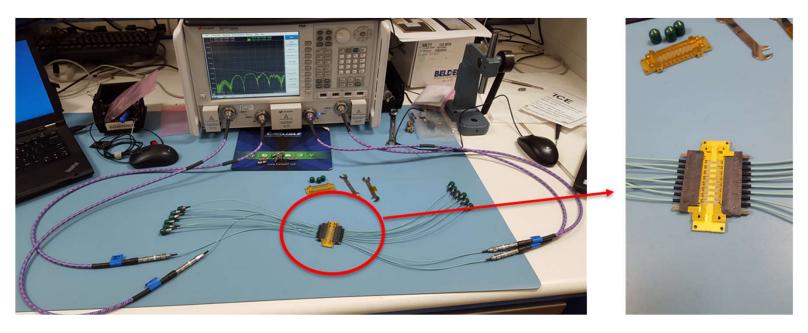
No Edge Platting







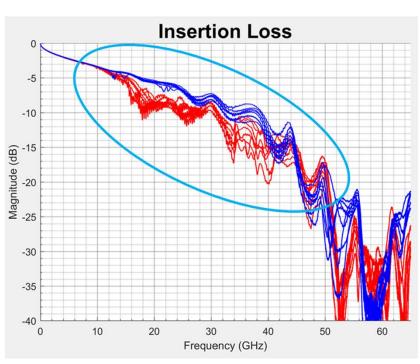
Edge Platting Experiment (2)

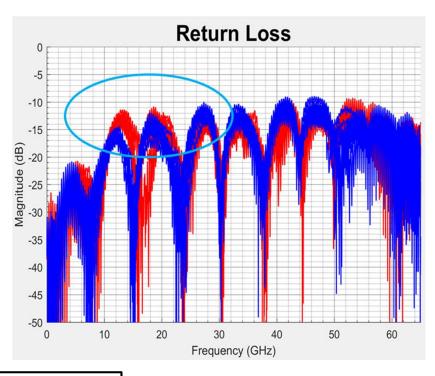


Keysight PNA Network Analyzer N5227A 10MHz-67GHz
 & 1.85mm standard calibration kit (85058B)



Edge Platting Experiment (3)

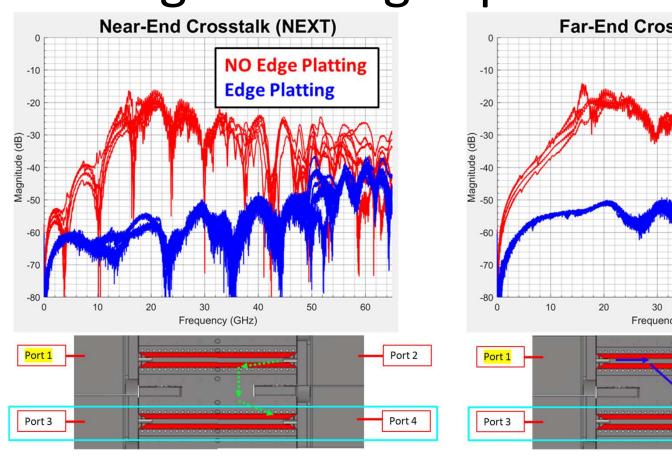


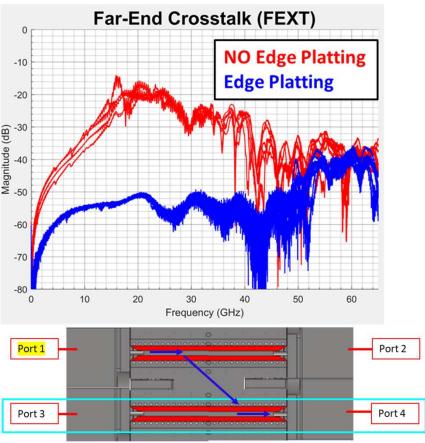


NO Edge Platting Edge Platting



Edge Platting Experiment (4)







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Conclusions

- Edge launch RF connectors require an optimized footprint to ensure performance.
- Some key challenges to address are:
 - Field leakage (resonances)
 - Ground and signal discontinuities
- Proposed Solutions
 - Match the size of the PCB dielectric layer and connector signal pin.
 - Proper ground structure alignment, including the vias to prevent field leakage
 - Edge platting:
 - Minimizes the ground discontinuities, Prevents field leakage



Next Steps

- Experiment with different edge platting configurations
- Revisit connector design to add redundant ground connections to reduce the effect of manufacturing tolerances on the board